

60V N-Channel Enhancement Mode MOSFET- ESD Protected

Voltage

60 V

Current

115 mA

Features

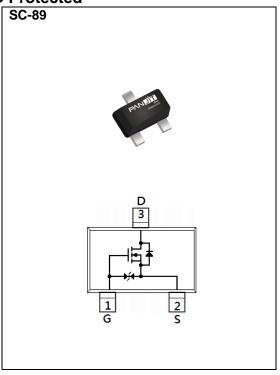
- $R_{DS(ON)}$, $V_{GS}@10V$, $I_D@500mA<3\Omega$
- $R_{DS(ON)}$, $V_{GS}@4.5V$, $I_{D}@200mA<4\Omega$
- Advanced Trench Process Technology
- High Density Cell Design For Ultra Low On-Resistance
- Very Low Leakage Current In Off Condition
- Specially Designed for Battery Operated Systems, Solid-State Relays Drivers: Relay, Displays, Memories, etc.
- ESD Protected
- Lead free in compliance with EU RoHS 2.0
- Green molding compound as per IEC 61249 standard

Mechanical Data

• Case: SC-89 Package

• Terminals : Solderable per MIL-STD-750, Method 2026

• Approx. Weight: 0.0026 grams



Maximum Ratings and Thermal Characteristics (T_A=25°C unless otherwise noted)

PARAMETER		SYMBOL	LIMIT	UNITS	
Drain-Source Voltage		V_{DS}	60	V	
Gate-Source Voltage		V _{GS}	<u>+</u> 20		
Continuous Drain Current(Note 4)		ΙD	115		
Pulsed Drain Current ^(Note 1)		I _{DM}	800	mA	
Power Dissipation	T _A =25°C		200	\4/	
	T _A =75°C	P _D	150	mW	
Operating Junction and Storage Temperature Range		T_{J},T_{STG}	-55~150	°C	
Thermal Resistance - Junction to Ambient ^(Note 3,4)		R _{θJA}	883	°C/W	



Electrical Characteristics (T_A=25°C unless otherwise noted)

PARAMETER	SYMBOL	TEST CONDITION	MIN.	TYP.	MAX.	UNITS	
Static							
Drain-Source Breakdown Voltage	BV _{DSS}	BV _{DSS} V _{GS} =0V, I _D =10uA	60	-	-		
Gate Threshold Voltage	V _{GS(th)}	V _{DS} =V _{GS} , I _D =250uA	1	-	2.5	V	
Drain-Source On-State Resistance	R _{DS(on)}	V _{GS} =4.5V, I _D =200mA	-	-	4	Ω	
		V _{GS} =10V, I _D =500mA	-	-	3		
Zero Gate Voltage Drain Current	I _{DSS}	V _{DS} =60V, V _{GS} =0V	-	-	1	uA	
Gate-Source Leakage Current	Igss	V _{GS} = <u>+</u> 20V, V _{DS} =0V	-	-	<u>+</u> 10		
Dynamic ^(Note 6)							
Total Gate Charge	Qg	V _{DS} =15V, I _D =200mA, V _{GS} =4.5V	-	-	0.8	nC	
Input Capacitance	Ciss	V _{DS} =25V, V _{GS} =0V, f=1MHz	-	-	35		
Output Capacitance	Coss		-	-	10	pF	
Reverse Transfer Capacitance	Crss		-	-	5		
Turn-On Delay Time	td _(on)	$V_{DD}{=}30V,\ R_{L}{=}150\Omega\ ,$ $I_{D}{=}200mA,\ V_{GEN}{=}10V,$ $R_{G}{=}10\Omega$	-	-	20	ns	
Turn-Off Delay Time	td _(off)		-	-	125	113	
Drain-Source Diode							
Continuous Diode Forward Current	Is		-	-	115	mA	
Pulsed Diode Forward Current	I _{SM}		-	-	- 800 IIIA		
Diode Forward Voltage	V _{SD}	I _S =200mA, V _{GS} =0V	-	0.82	1.3	V	

NOTES:

- 1. Pulse width<300us, Duty cycle<2%.
- 2. Essentially independent of operating temperature typical characteristics.
- 3. Repetitive rating, pulse width limited by junction temperature $T_{J(MAX)}=150^{\circ}$ C. Ratings are based on low frequency and duty cycles to keep initial $T_{J}=25^{\circ}$ C.
- 4. R_{BJA} is the sum of the junction-to-case and case-to-ambient thermal resistance where the case thermal reference is defined as the solder mounting surface of the drain pins mounted on a 1 inch FR-4 with 2oz. square pad of copper.
- 5. The maximum current rating is package limited.
- 6. Guaranteed by design, not subject to production testing.

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TYPICAL CHARACTERISTIC CURVES

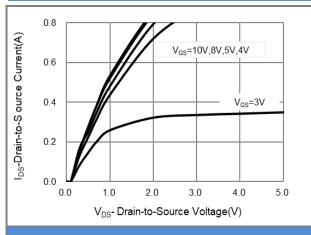


Fig.1 On-Region Characteristics

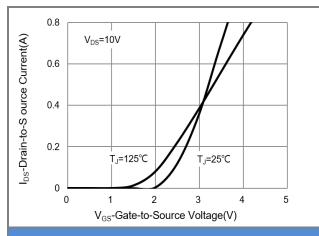


Fig.2 Transfer Characteristics

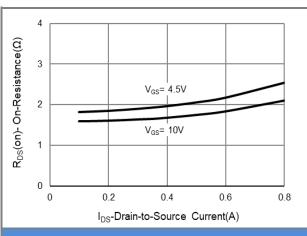


Fig.3 On-Resistance vs. Drain Current

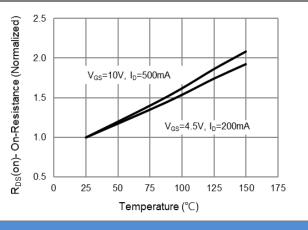
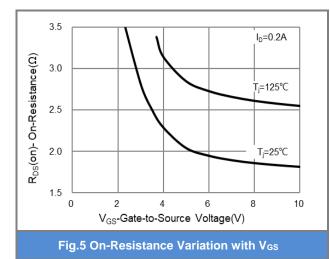
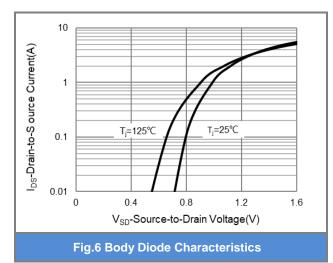


Fig.4 On-Resistance vs. Junction temperature







TYPICAL CHARACTERISTIC CURVES

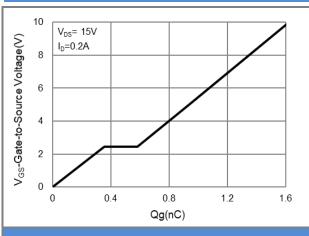


Fig.7 Gate-Charge Characteristics

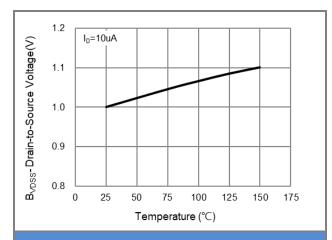


Fig.8 Breakdown Voltage Variation vs. Temperature

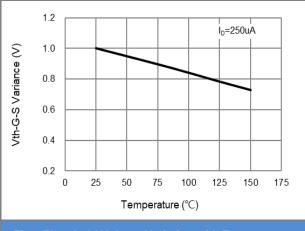


Fig.9 Threshold Voltage Variation with Temperature

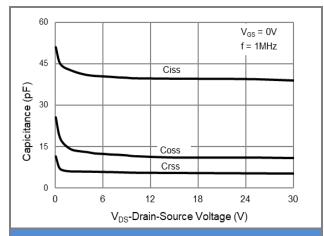


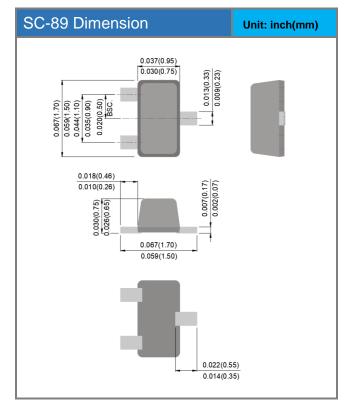
Fig.10 Capacitance vs. Drain-Source Voltage

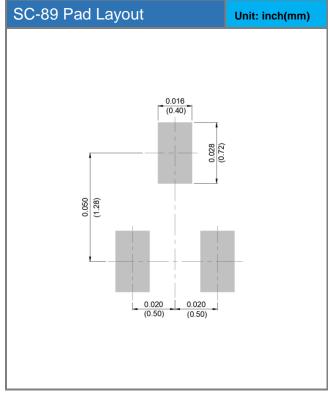


Product and Packing Information

Part No.	Package Type	Packing Type	Marking
2N7002KTB89	SC-89	4K pcs / 7" reel	27

Packaging Information & Mounting Pad Layout







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